

WIRING SUBSTRATE AND ELECTRONIC PARTS PACKAGING STRUCTURE

Abstract

In a wiring substrate of the present invention in which a bump of an electronic parts is bonded to a connection pad of a wiring pattern provided on an insulating film by an ultrasonic flip-chip packaging, a via hole into which a via post acting as a strut to support the connection pad upon the ultrasonic flip-chip packaging is filled is arranged in the insulating film under the connection pad.